

May 1991 Revised May 2005

74ACTQ16245 16-Bit Transceiver with 3-STATE Outputs

General Description

The ACTQ16245 contains sixteen non-inverting bidirectional buffers with 3-STATE outputs and is intended for bus oriented applications. The device is byte controlled. Each has separate control inputs which can be shorted together for full 16-bit operation. The T/\overline{R} inputs determine the direction of data flow through the device. The \overline{OE} inputs disable both the A and B ports by placing them in a high impedance state.

The ACTQ16245 utilizes Fairchild Quiet Series™ technology to guarantee quiet output switching and improved dynamic threshold performance. FACT Quiet Series™ features GTO™ output control for superior performance.

Features

- Utilizes Fairchild FACT Quiet Series technology
- Guaranteed simultaneous switching noise level and dynamic threshold performance
- Guaranteed pin-to-pin output skew
- Bidirectional non-inverting buffers
- Separate control logic for each byte
- 16-bit version of the ACTQ245
- Outputs source/sink 24 mA
- Additional specs for multiple output switching
- Output loading specs for both 50 pF and 250 pF loads

Ordering Code:

Order Number	Package Number	Package Description
74ACTQ16245SSC	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide
74ACTQ16245MTD	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

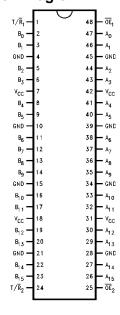
Logic Symbol



Pin Description

Pin Names	Description
ŌĒn	Output Enable Input (Active LOW)
T/R	Transmit/Receive Input
A ₀ -A ₁₅	Side A Inputs/Outputs
B ₀ -B ₁₅	Side B Outputs/Inputs

Connection Diagram



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Functional Description

The ACTQ16245 contains sixteen non-inverting bidirectional buffers with 3-STATE outputs. The device is byte controlled with each byte functioning identically, but independent of the other. The control pins can be shorted together to obtain full 16-bit operation. The following description applies to each byte. When the T/\overline{R} input is HIGH, then Bus A data is transmitted to Bus B. When the T/\overline{R} input is LOW, Bus B data is transmitted to Bus A. The 3-STATE outputs are controlled by an Output Enable (\overline{OE}_n) input for each byte. When \overline{OE}_n is LOW, the outputs are in 12-state mode. When \overline{OE}_n is HIGH, the outputs are in the high impedance mode, but this does not interfere with entering new data into the inputs.

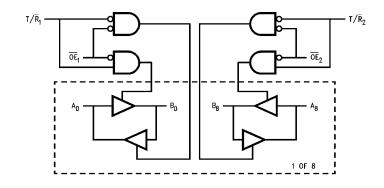
Truth Tables

Inp	outs					
OE ₁	T/R ₁	Outputs				
L	L	Bus B ₀ -B ₇ Data to Bus A ₀ -A ₇				
L	Н	Bus A ₀ -A ₇ Data to Bus B ₀ -B ₇				
Н	Х	HIGH-Z State on A ₀ -A ₇ , B ₀ -B ₇				

Inputs					
OE ₂	T/R ₂	Outputs			
L	L	Bus B ₈ -B ₁₅ Data to Bus A ₈ -A ₁₅			
L	Н	Bus A ₈ -A ₁₅ Data to Bus B ₈ -B ₁₅			
Н	X	HIGH-Z State on A ₈ -A ₁₅ , B ₈ -B ₁₅			

- H = HIGH Voltage Level
- L = LOW Voltage Level
- X = Immaterial
- Z = High Impedance

Logic Diagram



Absolute Maximum Ratings(Note 1)

Supply Voltage (V_{CC}) -0.5V to + 7.0V

DC Input Diode Current (I_{IK})

 $\begin{aligned} &V_I = -0.5V & -20 \text{ mA} \\ &V_I = V_{CC} + 0.5V & +20 \text{ mA} \end{aligned}$

DC Output Diode Current (I_{OK})

 $\begin{aligned} & V_O = -0.5V & -20 \text{ mA} \\ & V_O = V_{CC} + 0.5V & +20 \text{ mA} \\ & DC \text{ Output Voltage (V}_O) & -0.5V \text{ to V}_{CC} + 0.5V \\ & DC \text{ Output Source/Sink Current (I}_O) & \pm 50 \text{ mA} \end{aligned}$

DC V_{CC} or Ground Current

per Output Pin \pm 50 mA Storage Temperature $-65^{\circ}\text{C to} +150^{\circ}\text{C}$

Recommended Operating Conditions

V_{IN} from 0.8V to 2.0V

V_{CC} @ 4.5V, 5.5V

Note 1: Absolute maximum ratings are those values beyond which damage to the device may occur. The databook specifications should be met, without exception to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. Fairchild does not recommend operation of FACTTM circuits outside databook specifications.

DC Electrical Characteristics

Symbol	Parameter	V _{CC} T _A = +25°C		+25°C	$T_A = -40^{\circ}C \text{ to} + 85^{\circ}C$	Units	Conditions	
J,111501	r al allietei	(V)	Тур	Gua	ranteed Limits	Offics	Conditions	
V _{IH}	Minimum HIGH	4.5	1.5	2.0	2.0	V	V _{OUT} = 0.1V	
	Input Voltage	5.5	1.5	2.0	2.0	V	or V _{CC} – 0.1V	
V _{IL}	Maximum LOW	4.5	1.5	0.8	0.8	V	V _{OUT} = 0.1V	
	Input Voltage	5.5	1.5	0.8	0.8	V	or V _{CC} - 0.1V	
V _{OH}	Minimum HIGH	4.5	4.49	4.4	4.4	٧	I _{OUT} = -50 μA	
	Output Voltage	5.5	5.49	5.4	5.4	٧		
							$V_{IN} = V_{IL}$ or V_{IH}	
		4.5		3.86	3.76	V	I _{OH} = -24 mA	
		5.5		4.86	4.76		$I_{OH} = -24 \text{ mA (Note 2)}$	
V _{OL}	Maximum LOW	4.5	0.001	0.1	0.1	V	I _{OUT} = 50 μA	
	Output Voltage	5.5	0.001	0.1	0.1	ľ		
							$V_{IN} = V_{IL}$ or V_{IH}	
		4.5		0.36	0.44	V	I _{OL} = 24 mA	
		5.5		0.36	0.44		I _{OL} = 24 mA (Note 2)	
I _{OZT}	Maximum I/O	5.5		±0.5	±5.0	μА	$V_I = V_{IL}, V_{IH}$	
	Leakage Current	3.3		±0.5	±3.0	μΑ	$V_O = V_{CC}$, GND	
I _{IN}	Maximum Input Leakage Current	5.5		±0.1	±1.0	μА	$V_I = V_{CC}$, GND	
I _{CCT}	Maximum I _{CC} /Input	5.5	0.6		1.5	mA	$V_I = V_{CC} - 2.1V$	
I _{CC}	Max Quiescent Supply Current	5.5		8.0	80.0	μА	V _{IN} = V _{CC} or GND	
I _{OLD}	Minimum Dynamic	5.5			75	mA	V _{OLD} = 1.65V Max	
I _{OHD}	Output Current (Note 3)	5.5			-75	mA	V _{OHD} = 3.85V Min	
V_{OLP}	Quiet Output	5.0	0.5	0.8		V	Figure 1, Figure 2	
	Maximum Dynamic V _{OL}	3.0	0.5	0.0		•	(Note 5)(Note 6)	
V _{OLV}	Quiet Output	5.0	-0.5	-0.85		V	Figure 1, Figure 2	
	Minimum Dynamic V _{OL}	3.0	-0.5	-0.03		V	(Note 5)(Note 6)	
V_{OHP}	Maximum	5.0	V . 10	V _{OH} + 1.5		V	Figure 1, Figure 2	
	Overshoot	5.0	V _{OH} + 1.0	VOH + 1.5		V	(Note 4)(Note 6)	
V _{OHV}	Minimum	5.0	V 10	V _{OH} - 1.8		V	Figure 1, Figure 2	
	V _{CC} Droop	3.0	VOH - 1.0	VOH - 1.0		•	(Note 4)(Note 6)	
V_{IHD}	Minimum HIGH Dynamic Input Voltage Level	5.0	1.7	2.0		V	(Note 4)(Note 7)	
V _{ILD}	Maximum LOW Dynamic Input Voltage Level	5.0	1.2	0.8		V	(Note 4)(Note 7)	

Note 2: All outputs loaded; thresholds associated with output under test.

 $[\]textbf{Note 3:} \ \ \text{Maximum test duration 2.0 ms; one output loaded at a time.}$

Note 4: Worst case package.

Note 5: Maximum number of outputs that can switch simultaneously is n. (n – 1) outputs are switched LOW and one output held LOW.

Note 6: Maximum number of outputs that can switch simultaneously is n. (n – 1) outputs are switched HIGH and one output held HIGH.

Note 7: Max number of data inputs (n) switching. (n – 1) input switching 0V to 3V input under test switching 3V to threshold (V_{ILD})

AC Electrical Characteristics

		V _{CC}		$T_A = +25$ $^{\circ}C$		T _A = -40°	C to +85°C	
Symbol	Parameter	(V)		$\textbf{C}_{\boldsymbol{L}} = \textbf{50 pF}$		C _L =	50 pF	Units
		(Note 8)	Min	Тур	Max	Min	Max	
t _{PLH}	Propagation Delay	5.0	3.2	5.7	8.4	3.2	9.0	20
t _{PHL}	A_n , B_n to B_n , A_n	5.0	2.6	5.1	7.9	2.6	8.4	ns
t _{PZH}	Output Enable	5.0	3.7	6.4	9.4	2.7	10.0	ns
t _{PZL}	Time	5.0	4.1	7.4	10.5	3.4	11.6	115
t _{PHZ}	Output Disable	5.0	2.2	5.4	8.7	2.2	9.3	no
t _{PLZ}	Time	5.0	2.0	5.2	8.2	2.0	8.8	ns

Note 8: Voltage Range 5.0 is 5.0V ± 0.5V.

Extended AC Electrical Characteristics

			TA	= -40°C to +8	35°C			
Symbol Parameter			C _L = 50 pF 16 Outputs Switching			$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $C_L = 250 \text{ pF}$		Units
		v _{cc}						
		(V)	(Note 11)		(Note 12)			
		(Note 9)	Min	Тур	Max	Min	Max	
t _{PLH}	Propagation Delay	5.0	4.2		11.9	5.9	14.6	ns
t _{PHL}	Data to Output	5.0	3.5		9.9	5.0	13.4	115
t _{PZH}	Output Enable Time	5.0	4.5		11.4	(Note 13)		ns
t_{PZL}		5.0	4.4		12.2			115
t _{PHZ}	Output Disable Time	5.0	3.5		9.3	(Note 14)		ns
t_{PZL}		5.0	3.1		8.8			
t _{OSHL}	Pin to Pin Skew	5.0			1.2			ns
(Note 10)	HL Data to Output							
t _{OSLH}	Pin to Pin Skew	5.0			1.3			ns
(Note 10)	LH Data to Output							
t _{OST}	Pin to Pin Skew	5.0			3.0			ns
(Note 10)	LH/HL Data to Output							

Note 9: Voltage Range 5.0 is 5.0V ± 0.5V.

Note 10: Skew is defined as the absolute value of the difference between the actual propagation delays for any two separate outputs of the same device. The specification applies to any outputs switching HIGH-to-LOW (t_{OSHL}), LOW-to-HIGH (t_{OSLH}), or any combination switching LOW-to-HIGH and/or HIGH-to-LOW (t_{OST}).

Note 11: This specification is guaranteed but not tested. The limits apply to propagation delays for all paths described switching in phase (i.e., all LOW-to-HIGH, HIGH-to-LOW, etc.).

Note 12: This specification is guaranteed but not tested. The limits represent propagation delays with 250 pF load capacitors in place of the 50 pF load capacitors in the standard AC load. This specification pertains to single output switching only.

Note 13: 3-STATE delays are load dominated and have been excluded from the datasheet.

Note 14: The Output Disable Time is dominated by the RC network (500 Ω , 250 pF) on the output and has been excluded from the datasheet.

Capacitance

Symbol	Parameter	Тур	Units	Conditions
C _{IN}	Input Pin Capacitance	4.5	pF	V _{CC} = 5.0V
C _{PD}	Power Dissipation Capacitance	25	pF	$V_{CC} = 5.0V$

FACT Noise Characteristics

The setup of a noise characteristics measurement is critical to the accuracy and repeatability of the tests. The following is a brief description of the setup used to measure the noise characteristics of FACT.

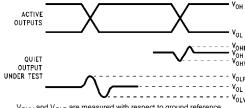
Equipment:

Hewlett Packard Model 8180A Word Generator PC-163A Test Fixture

Tektronics Model 7854 Oscilloscope

Procedure:

- 1. Verify Test Fixture Loading: Standard Load 50 pF, 500Ω
- 2. Deskew the HFS generator so that no two channels have greater than 150 ps skew between them. This requires that the oscilloscope be deskewed first. It is important to deskew the HFS generator channels before testing. This will ensure that the outputs switch simultaneously.
- 3. Terminate all inputs and outputs to ensure proper loading of the outputs and that the input levels are at the correct voltage.
- Set the HFS generator to toggle all but one output at a frequency of 1 MHz. Greater frequencies will increase DUT heating and effect the results of the measurement.



 $\rm V_{OHV}$ and $\rm V_{OLP}$ are measured with respect to ground reference.

Input pulses have the following characteristics: f = 1 MHz, $t_r = 3 \text{ ns}$, $t_f = 3 \text{ ns}, \text{ skew} < 150 \text{ ps}$

FIGURE 1. Quiet Output Noise Voltage Waveforms

Set the HFS generator input levels at 0V LOW and 3V HIGH for ACT devices and 0V LOW and 5V HIGH for AC devices. Verify levels with an oscilloscope.

V_{OLP}/V_{OLV} and V_{OHP}/V_{OHV}:

- · Determine the quiet output pin that demonstrates the greatest noise levels. The worst case pin will usually be the furthest from the ground pin. Monitor the output voltages using a 50Ω coaxial cable plugged into a standard SMB type connector on the test fixture. Do not use an active FET probe.
- Measure V_{OLP} and V_{OLV} on the quiet output during the worst case transition for active and enable. Measure $V_{\mbox{\scriptsize OHP}}$ and $V_{\mbox{\scriptsize OHV}}$ on the quiet output during the worst case active and enable transition.
- Verify that the GND reference recorded on the oscilloscope has not drifted to ensure the accuracy and repeatability of the measurements.

V_{ILD} and V_{IHD}:

- Monitor one of the switching outputs using a 50Ω coaxial cable plugged into a standard SMB type connector on the test fixture. Do not use an active FET probe.
- First increase the input LOW voltage level, $V_{\text{IL}},$ until the output begins to oscillate or steps out a min of 2 ns. Oscillation is defined as noise on the output LOW level that exceeds V_{IL} limits, or on output HIGH levels that exceed $V_{\mbox{\scriptsize IH}}$ limits. The input LOW voltage level at which oscillation occurs is defined as V_{ILD}.
- Next decrease the input HIGH voltage level, V_{IH} , until the output begins to oscillate or steps out a min of 2 ns. Oscillation is defined as noise on the output LOW level that exceeds V_{IL} limits, or on output HIGH levels that exceed V_{IH} limits. The input HIGH voltage level at which oscillation occurs is defined as VIHD.
- Verify that the GND reference recorded on the oscilloscope has not drifted to ensure the accuracy and repeatability of the measurements.

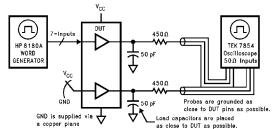


FIGURE 2. Simultaneous Switching Test Circuit

Physical Dimensions inches (millimeters) unless otherwise noted 0.620 - 0.630 [15.75 - 16.00] - A -0.398 - 0.417 [10.10 - 10.60] LEAD #1 O 0.010[0.25] C B S A S IDENT 0.291 - 0.299 [7.40 - 7.59] <u>-B-</u>↓ 0.005 - 0.009 [0.13 - 0.22] 24 0.025 [0.635] TYP GAUGE PLANE: 0.010 0.020±0.003 [0.51±0.08] TYP _0.020 - 0.040 _[0.51 - 1.01] 0.008 - 0.012 [0.21 - 0.30] TYP DETAIL E TYP O 0.0031[0.08]W C A S BS 45° x 0.015 - 0.025 [0.39 - 0.63] 0.096 - 0.108 [2.44 - 2.74] SEATING PLANE -SEE DETAIL E 0.004[0.10] 0.025 [0.635] TYP 0.10 [0.25] MIN TYP-MS48A (REV E) 48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide Package Number MS48A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 12.50±0.10 0.40 TYP -B-0±0.10 4.60 -B.10 4.05 O.2 C B A ALL LEAD TIPS PIN #1 IDENT LAND PATTERN RECOMMENDATION △ 0.1 C SEE DETAIL A 0.90+0.15 0.09-0.20 0.10±0.05 0.50 0.17-0.27 ♦ 0.13\(\text{A} \) A B\(\text{S} \) C\(\text{S} \) 12.00' TOP & BOTTOM R0.16 DIMENSIONS ARE IN MILLIMETERS GAGE PLANE 0.25 NOTES: A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION ED. DATE 4/97. B. DIMENSIONS ARE IN MILLIMETERS. SEATING PLANE 0.60±0.10 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. DETAIL A MTD48REVC

48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

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